

Abstract

The present invention proposes a smart automatic recording system and method for monitoring wafer fragmentation, which system comprises a plurality of photographing devices, a multiple-image transmitter, a multiple-
5 image receiver, and a PC. The photographing devices are used to monitor the circumstances when wafers are polished. The photographed images are then transferred to the multiple-image receiver by the multiple-image transmitter. After the multiple-image receiver receives the image signals, it merges the images captured at the same time into the same image frame. Next, the
10 multiple-image receiver transfers the image signal to the input terminal of an image-capturing card in the PC. The PC also receives the wafer-entry and wafer-exit signals and the signal of wafer fragmentation transferred from the I/O port of the polishing apparatus. The present invention can be exploited to facilitate judgement, diagnosis, genuine factor verification, or engineering
15 improvement and management for associated technicians.